

(19) World Intellectual Property Organization
International Bureau



(43) International Publication Date
9 June 2005 (09.06.2005)

PCT

(10) International Publication Number
WO 2005/053039 A3

(51) International Patent Classification⁷: **H01L 31/042**,
31/05, 31/048

(21) International Application Number:
PCT/JP2004/017985

(22) International Filing Date:
26 November 2004 (26.11.2004)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
2003-398197 27 November 2003 (27.11.2003) JP
2003-431603 25 December 2003 (25.12.2003) JP
2004-096815 29 March 2004 (29.03.2004) JP

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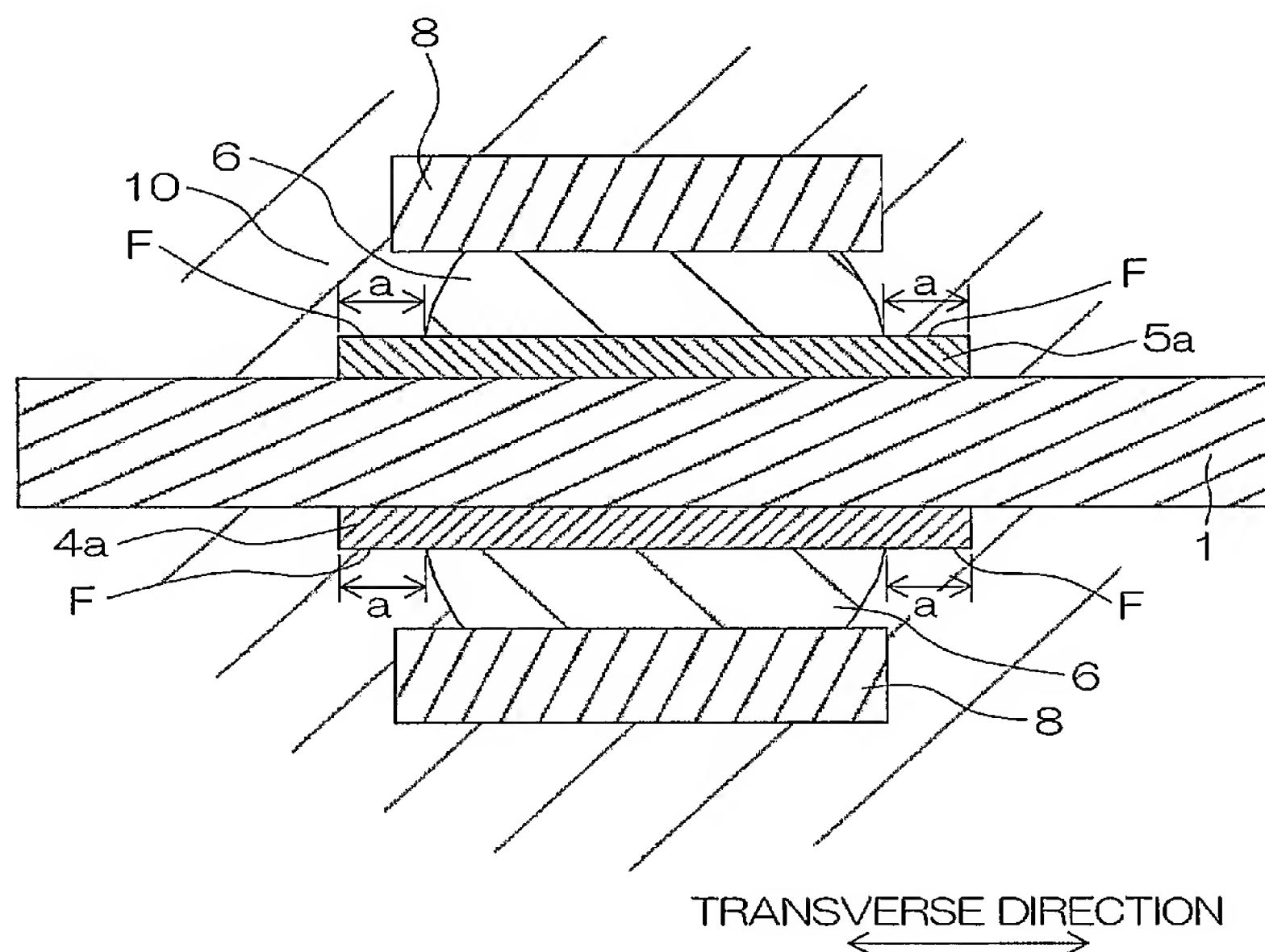
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(81) Designated States (unless otherwise indicated, for every kind of national protection available): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW.

(84) Designated States (unless otherwise indicated, for every kind of regional protection available): ARIPO (BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI,

[Continued on next page]

(54) Title: SOLAR CELL MODULE



(57) Abstract: The largest stress is created in the vicinity of the boundary between an edge of a bus bar electrode in a solar cell and a surface of a semiconductor substrate, and stresses are easily concentrated. Accordingly, defects such as micro cracks occur in the semiconductor substrate, which develop into a large craze with the defects as its starting point. In connecting bus bar electrodes 4a and 5a in the solar cell by an inner lead 8, therefore, a solder 6 is not brought into contact with edges along the longitudinal direction of the bus bar electrodes 4a and 5a and portions F from the edges to a predetermined distance a inward therefrom, and is brought into direct contact with a filler 10.

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FR, GB, GR, HU, IE, IS, IT, LU, MC, NL, PL, PT, RO, SE, SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.

Published:

- *with international search report*
- *before the expiration of the time limit for amending the claims and to be republished in the event of receipt of amendments*

(88) Date of publication of the international search report:

16 March 2006